Abstracts

Simulation of Multi-Chip Module Package Resonance Using Commercial Finite Element Electromagnetic Software

R. Clark, A. Agrawal and S. Miller. "Simulation of Multi-Chip Module Package Resonance Using Commercial Finite Element Electromagnetic Software." 1995 MTT-S International Microwave Symposium Digest 95.3 (1995 Vol. III [MWSYM]): 1211-1214.

Techniques have been developed to predict package resonance frequencies in multiple cavity, MMIC based, T/R modules, using the HP High Frequency Structure Simulator package. This method accounts for partially filled waveguide modes, perturbations due to GaAs MMICS and their metal spacers, and the effects of imperfect cavity end walls. Calculated results are compared to measured package resonances and module performance data.

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